



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

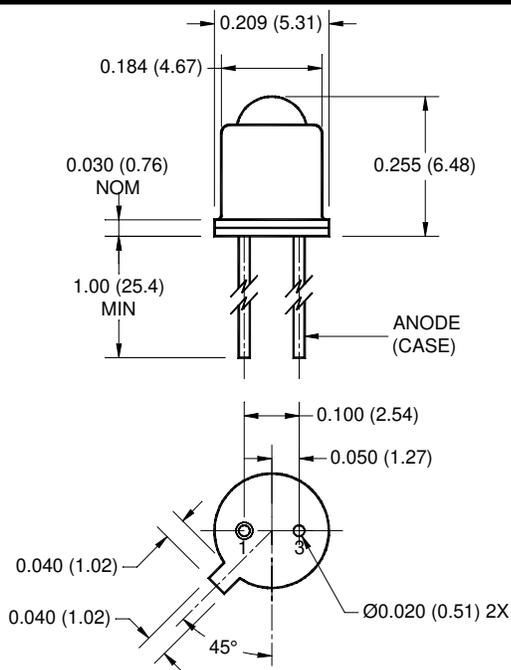
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PACKAGE DIMENSIONS



NOTES:

1. Dimensions for all drawings are in inches (mm).
2. Tolerance of $\pm .010$ (.25) on all non-nominal dimensions unless otherwise specified.

DESCRIPTION

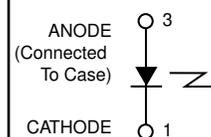
The CQX14/16 are 940 nm LEDs in a narrow angle, TO-46 packages.



FEATURES

- Good optical to mechanical alignment
- Mechanically and wavelength matched to the TO-18 series phototransistor
- Hermetically sealed package
- High irradiance level
- European "Pro Electron" registered

SCHEMATIC



1. Derate power dissipation linearly 1.70 mW/°C above 25°C ambient.
2. Derate power dissipation linearly 13.0 mW/°C above 25°C case.
3. RMA flux is recommended.
4. Methanol or isopropyl alcohols are recommended as cleaning agents.
5. Soldering iron tip 1/16" (1.6mm) minimum from housing.
6. As long as leads are not under any stress or spring tension
7. Total power output, P_O, is the total power radiated by the device into a solid angle of 2 π steradians.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise specified)

Parameter	Symbol	Rating	Unit
Operating Temperature	T _{OPR}	-65 to +125	°C
Storage Temperature	T _{STG}	-65 to +150	°C
Soldering Temperature (Iron) ^(3,4,5 and 6)	T _{SOL-I}	240 for 5 sec	°C
Soldering Temperature (Flow) ^(3,4 and 6)	T _{SOL-F}	260 for 10 sec	°C
Continuous Forward Current	I _F	100	mA
Forward Current (pw, 1μs; 200Hz)	I _F	10	A
Reverse Voltage	V _R	3	V
Power Dissipation (T _A = 25°C) ⁽¹⁾	P _D	170	mW
Power Dissipation (T _C = 25°C) ⁽²⁾	P _D	1.3	W

ELECTRICAL / OPTICAL CHARACTERISTICS (T_A = 25°C) (All measurements made under pulse conditions)

PARAMETER	TEST CONDITIONS	SYMBOL	MIN	TYP	MAX	UNITS
Peak Emission Wavelength	I _F = 100 mA	λ _P	—	940	—	nm
Emission Angle at 1/2 Power	I _F = 100 mA	θ	—	±8	—	Deg.
Forward Voltage	I _F = 100 mA	V _F	—	—	1.7	V
Reverse Leakage Current	V _R = 3 V	I _R	—	—	10	μA
Total Power CQX14 ⁽⁷⁾	I _F = 100 mA	P _O	5.4	—	—	mW
Total Power CQX16 ⁽⁷⁾	I _F = 100 mA	P _O	1.5	—	—	mW
Rise Time 0-90% of output		t _r	—	1.0	—	μs
Fall Time 100-10% of output		t _f	—	1.0	—	μs

Figure 1. Power Output vs. Input Current

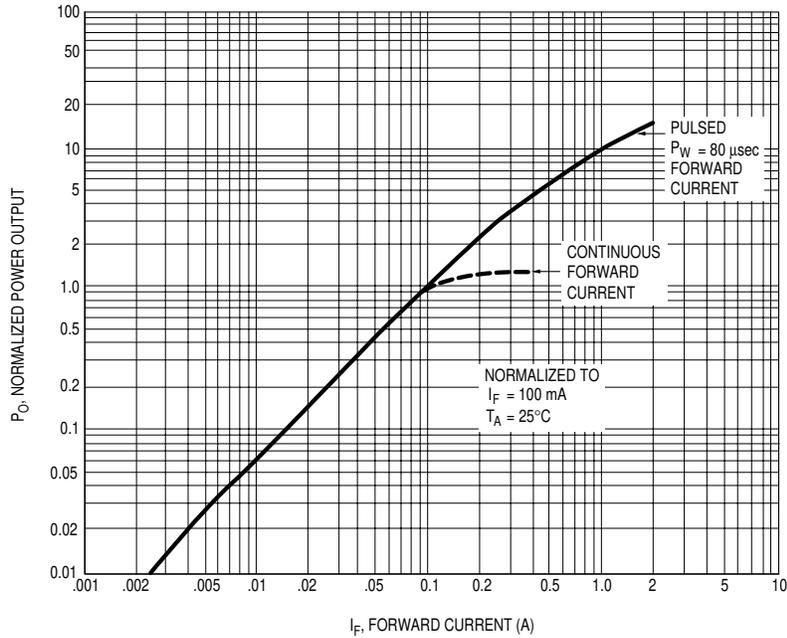


Figure 2. Power Output vs. Temperature

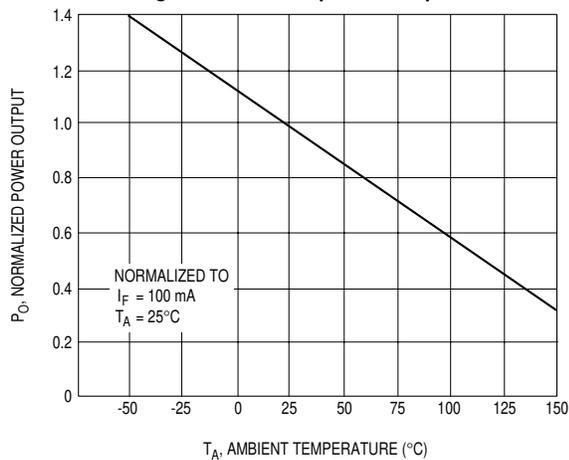


Figure 3. Forward Voltage vs. Forward Current

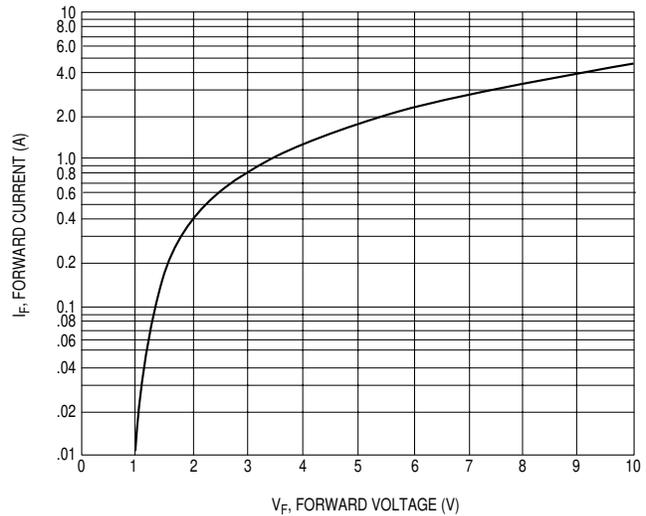


Figure 4. Forward Voltage vs. Forward Current

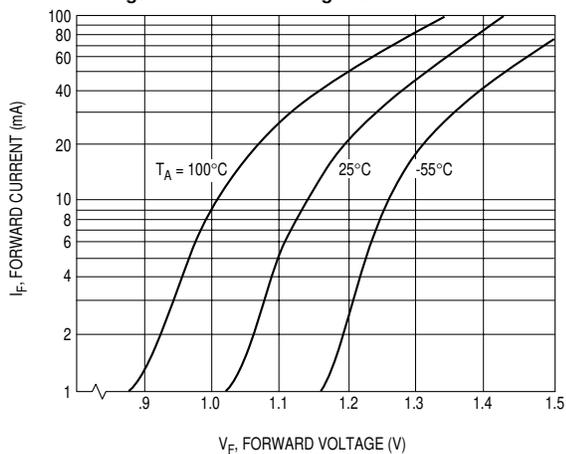
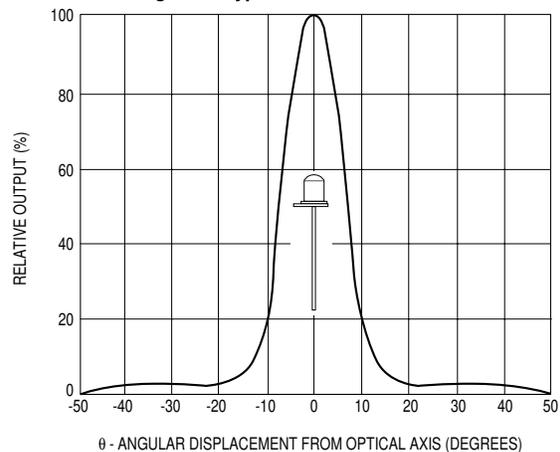


Figure 5. Typical Radiation Pattern



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